

RESPONSE TO RESTRICTION REQUIREMENT AND PRELIMINARY AMENDMENT

Serial Number: 10/607,738

Filing Date: June 26, 2003

Title: MULTI-LAYER POLYMER-SOLDER HYBRID THERMAL INTERFACE MATERIAL FOR INTEGRATED HEAT SPREADER  
AND METHOD OF MAKING SAME

Assignee: Intel Corporation

Page 7

Dkt: 884.832US1

REMARKS

This responds to the Restriction Requirement mailed on March 4, 2005.

Claims 11-24 were cancelled, claims 25-38 were added; as a result, claims 1-10 and 25-38 are now pending in this application.

No new matter was added by these amendments. The new claims are drawn to the elected claims; 1-10. Support for the new claims comes from pages 7-13, FIGs. 1A-3B, 5A-8B, and elsewhere throughout the disclosure.

The Examiner is invited to telephone Applicant's attorney, John Greaves at (801) 278-9171, or Applicant's below-named representative at (612) 373-6970 to facilitate the prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

SABINA J. HOULE ET AL.

By their Representatives,

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Date April 4, 2005 By Ann M. McCrackin  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 4 day of April, 2005.

Dennis J. Kamph  
Name

[Signature]  
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